

Appl. No. 10/711,794
Amdt. dated May 26, 2006
Reply to Office action of January 27, 2006

Amendments to the Claims:

Listing of Claims:

Claim 1 (currently amended): A package structure comprising:

- 5 a lead frame having a plurality of first leads, each of which includes a first recession,
 and a second recession;
 at least a semiconductor chip; and
 a plurality of first solder joints respectively positioned in the first recessions for
 connecting the semiconductor chip to the lead frame;
10 at least one passive device having a plurality of outputs respectively positioned in
 the second recessions; and
 a plurality of second solder joints respectively positioned in the second recessions
 for connecting the passive device to the lead frame.

15 Claim 2 (cancelled)

 Claim 3 (cancelled)

 Claim 4 (currently amended): The package structure of claim 3, wherein the passive
20 device is an electrical resistor, a capacitor, or an inductor.

 Claim 5 (cancelled)

 Claim 6 (cancelled)

25 Claim 7 (cancelled)

 Claim 8 (cancelled)

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Claim 9 (currently amended): The package structure of claim 31 wherein the second solder joints are comprised of tin or tin alloy.

5 Claim 10 (previously presented): The package structure of claim 1 wherein the lead frame comprises a die pad connected to the semiconductor chip for radiating the heat produced by the semiconductor chip by serving as a heat sink.

10 Claim 11 (previously presented): The package structure of claim 10 wherein the die pad comprises a ground pad connected to both ground and the semiconductor chip.

Claim 12 (previously presented): The package structure of claim 1 wherein the first solder joints are comprised of tin or tin alloy.

Claim 13 (currently amended): The package structure comprising:
a lead frame having a plurality of first leads, wherein at least two of the first leads
15 comprises a first recession;
at least a passive device, wherein each output of the passive device is respectively positioned in the first recession; and
a plurality of first solder joints respectively positioned in the first recessions for connecting the passive device to the lead frame.

20 Claim 14 (previously presented): The package structure of claim 13 wherein the package structure further comprises a semiconductor chip and a plurality of leading wires, wherein the semiconductor chip is connected to the leading wires.

Claim 15 (previously presented): The package structure of claim 13 wherein the passive device is an electrical resistor, a capacitor, or an inductor.
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Claim 16 (previously presented): The package structure of claim 13 wherein the first solder joints are comprised of tin or tin alloy.